

CLAIMS

1. A foamed adhesive comprising at least one resin emulsion.
2. The foamed adhesive of claim 1 where the adhesive is foamed from about 20 to about 60% weight per volume.
3. The foamed adhesive of claim 1 wherein the at least one resin emulsion is a polyvinyl acetate emulsion.
4. The foamed adhesive of claim 3 comprising a blend of at least two polyvinyl acetates.
5. The foamed adhesive of claim 4 wherein at least one polyvinyl acetate is prepared by batch polymerization and at least one polyvinyl acetate is prepared by continuous polymerization.
6. The foamed adhesive of claim 3 further comprising a filler.
7. The foamed adhesive of claim 6 wherein the filler is a polysaccharide.
8. The foamed adhesive of claim 7 wherein the polysaccharide is a starch.
9. The foamed adhesive of claim 1 comprising from about 55 to about 85% of said at least one resin emulsion and from about 5 to about 20% of a filler.
10. The foamed adhesive of claim 9 further comprising a surface active agent, a defoamer, a preservative or a UV indicator.
11. An article of manufacture comprising the foamed adhesive of claim 1.

12. The article of claim 11 which comprises a wood composite and a high pressure laminate, wherein the wood composite is bonded to the high pressure laminate using said foamed adhesive.

13. The article of claim 1 where the adhesive is foamed from about 20 to about 60% weight per volume.

14. The article of claim 11 wherein the adhesive comprises at least one polyvinyl acetate.

15. The article of claim 14 wherein the foamed adhesive further comprises a polysaccharide filler.

16. The article of claim 15 wherein the polysaccharide is a starch.

17. The article of 16 wherein the adhesive further comprising a surface active agent, a defoamer, a preservative or a UV indicator.

18. The article of claim 17 which is a countertop.

19. A method for bonding materials together which comprises applying the foamed adhesive composition of claim 1 to a first substrate, bringing a second substrate in contact with the adhesive composition applied to the first substrate, and subjecting the applied composition to conditions which will allow the composition to cool and form a set bond, wherein one of said first or second substrate is a wood composite and the other of said first or second substrate is a high pressure laminate.

20. The method of claim 11 wherein said conditions which will allow the composition to cool and form a set bond comprises heat and pressure.